

High Precision Epoxy molding compound (for Injection molding)

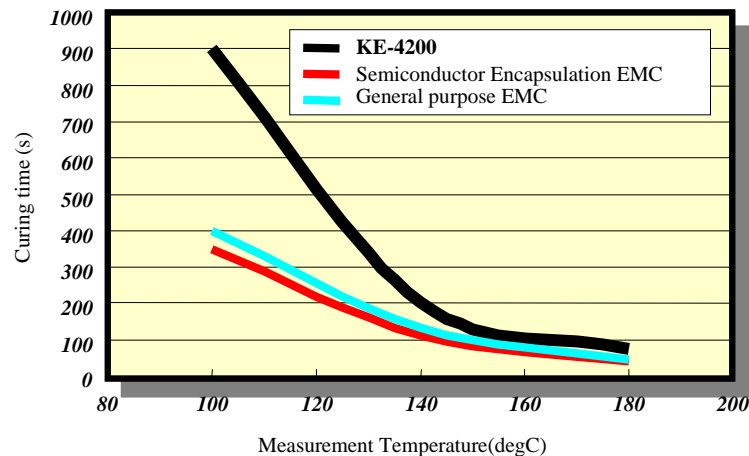
Increase the freedom of designing and provides superior cost performance.

Features

- 1) Least anisotropic structure, high dimensional accuracy molded parts
- 2) High mechanical modulus, lower deflection molded parts
- 3) Excellent electrical properties, especially good insulation properties, excellent heat resistant, excellent moldability, excellent storage behavior

Application

- a) Optical fiber connector components
- b) Printer parts



Unique Technology



This EMC is can respond injection molding which is controllable to a few micron order .

Dimensional Stability of KE-4200

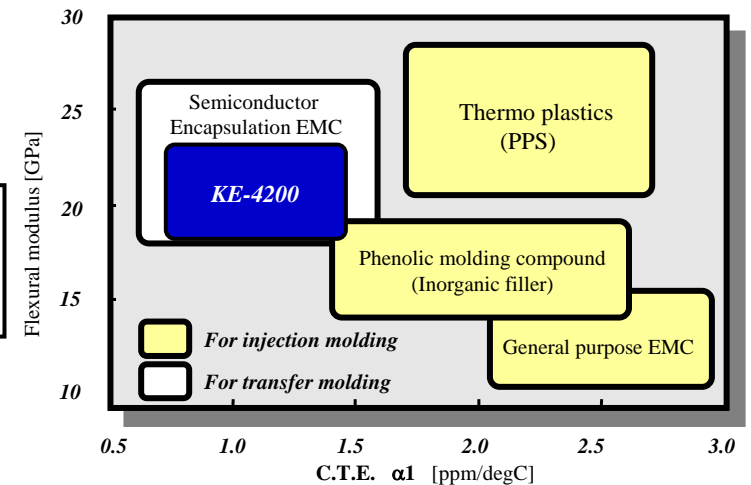
		Unit	KE-4200
Mold Shrinkage	Horizontal	%	0.09
	Vertical	%	0.07
	Average	%	0.08
Dimension measurement (6s/X)	Curing time 30s	%	0.06
	Curing time 90s		0.06
	Curing time 120s		0.07

Positioning of various molding compounds

Unique Technology



*Application of Injection Molding technology
 *Application of Semiconductor Encapsulation EMC Technology



Thermosetting Molded Parts

High precision molded parts using Epoxy molding compound KE-4200

Features

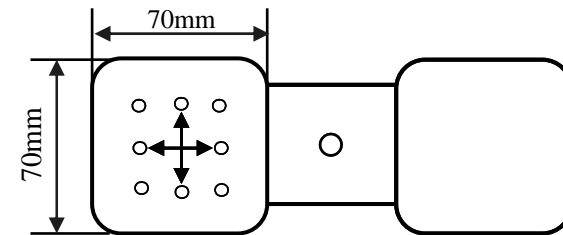
- 1) Least anisotropic structure, high dimensional accuracy molded parts
 Mold shrinkage: 0.08 %
- 2) High mechanical modulus, lower deflection molded parts
 Flexural modulus: 22 GPa
- 3) Lower coefficient of thermal expansion and enables to decrease warpage and strain
 Coefficient of thermal expansion: 1.1×10^{-5}

Application

- a) Optical connector components, printer parts

Dimensional stability

Configuration of the measured parts



1.5 mm diameter. Distance between hole to hole(center) is 30 mm.
 Thickness: 2.5 mm

Dimension measurement (6sigma/X)	curing time 30 sec	%	0.06
	curing time 90 sec		0.06
	curing time 120 sec		0.07

Properties comparison of KE-4200 molded parts with PPS

Item	Unit	KE-4200 High dimensional accuracy	PPS Glass 40%
Specific gravity	-	2.00	1.66
Mold shrinkage	%	0.08	0.68
Flexural modulus	GPa	22	13.5
Coefficient of thermal expansion	1 / °C	1.1×10^{-5}	2.0×10^{-5}